PEC. NO.: PS-51503-XXXXX-XXX		XXX-XXX	REVISION:	Р			
RODUCT NA	ME:	0.5/0.8/1.0MM PITCH EASY ON FPC CONN.					
		SMT R/A BOTTO	M CONTACT TYPE				
RODUCT NO:	51502 /	51502 / 51503 / 51530/ 51533 / 51639 SERIES					
		51540/ 51550 /51561/51574/ 51586 /51575 SERIES					
	51569/5	51570/51581/51605 /	51678 /51686/52500SER	RIES			
PREPARED:		CHECKED:	APPROV	ED:			
		DATE:	DATE:				
DATE: 2021/01	/20	2021/01	/20 2	2021/01/20			

2010/10/31 TR-FM-73015L

	Aces	P/N: 51503 series						
TITLE: 0.5/0.8/1.0MM PITCH EASY ON FPC CONN. SMT R/A BOTTOM CONTACT TYPE								
RELEASE DATE: 2021/01/20	REVISION: P	ECN No: ECN-001592	PAGE: 2 OF 10					
 2 SCOPE 3 APPLICABLE D 4 REQUIREMENT 5 PERFORMANC 6 INFRARED REI 7 PRODUCT QUA 	OCUMENTS TS E FLOW CONDITION ALIFICATION AND	TEST SEQUENCE						

EASE DATE			R/A BOTTOM CON	VIACI I I I I		
	: 2021/01/20	REVISION: P E	ECN No: ECN-001592	PA	GE: 3 OF 10	
Revisi	on History					
Rev.	ECN #	Revision Descr	iption	Prepared	Date	
1	ECN-1006010	FOR APD990120(51503 SEI	RIES)	RYAN	2010/06/01	
2	ECN-1101197	FOR APD990334&APD1000 51502&51530 SERIES		RYAN	2011/01/24	
3	ECN-1103097	FOR APD1000081 ADD 515	33 SERIES	HUANTY	2011/03/17	
0	ECN-1106036	RELEASE	HUANTY	2011/06/02		
Α	ECN-1106229	FOR APD1000152 ADD 515	FOR APD1000152 ADD 51540 SERIES			
В	ECN-1110304	FOR APD1000403 ADD 515	FOR APD1000403 ADD 51550 SERIES			
С	ECN-1206014	FOR APD1010218 ADD 515	RYAN	2012/06/14		
D	ECN-1208163	FOR APD1010443 ADD 515	74 SERIES	GAVIN	2012/08/22	
E	ECN-1211144	FOR APD1010559 ADD 515	86 SERIES	GAVIN	2012/11/12	
F	ECN-1212175	FOR AP D 1010512 ADD 515	581 SERIES	WAN.BO	2012/12/11	
G	ECN-1307460	FOR APD1020119 ADD 516	05 SERIES	WAN.BO	2013/07/25	
Н	ECN-1401127	ADD Working voltage		YANGYANG	2014/01/10	
J	ECN-1501117	FOR <u>APD1030223</u> ADD 5 ⁻	1639 SERIES	COCOYU	2015/01/08	
K	ECN-1507163	FOR APD1010446 ADD 51	575 SERIES	COCOYU	2015/07/14	
L	ECN-1510259	FOR APD1040146 ADD 516	78 SERIES	XUBIN	2015/10/22	
М	ECN-1512380	FOR APD1040296 ADD 516 UPDATE TEST GROUP	86 SERIES	XUBIN	2015/12/25	
N	ECN-2006149	FOR APP1090228 ADD Sal plating 3 u"	t Spray: Gold	SUNYAJIE	2020/05/27	
Р	ECN-001592	ADD Salt Spray (Gold plating 1	u" for 8 hours).	GUOEI	2021/01/20	

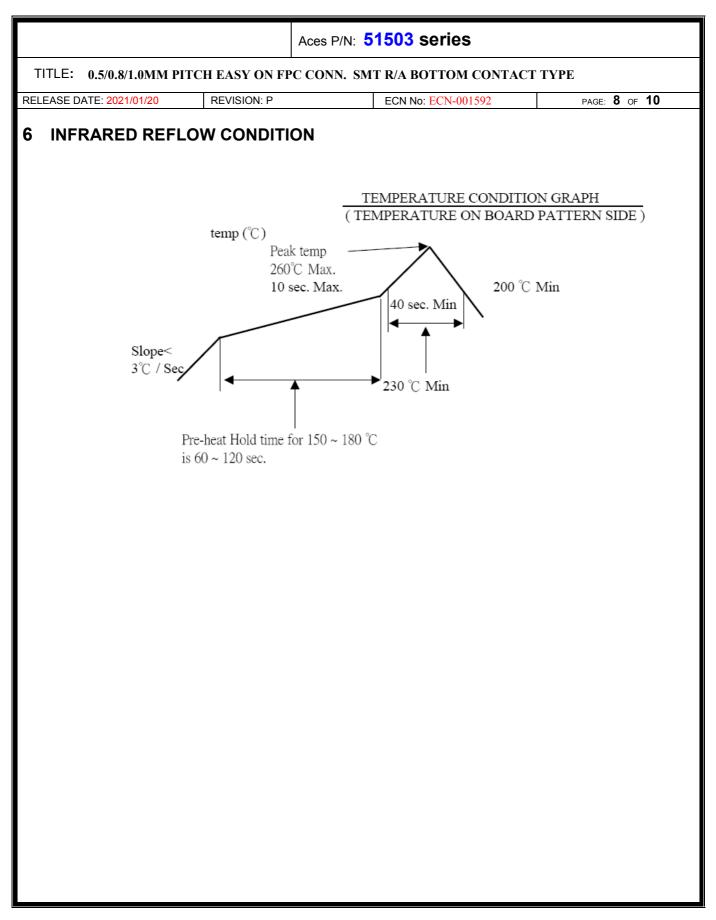
		Ace	es P/N: 51503 serie	S						
Т	TITLE: 0.5/0.8/1.0MM PITCH EASY ON FPC CONN. SMT R/A BOTTOM CONTACT TYPE									
REL	EASE DATE: 2021/01/20	REVISION: P	ECN No: ECN-(001592	PAGE: 4 OF 10					
2	SCOPE This specification cov 0.5/0.8/1.0MM PITCH				CT TYPE					
3	EIA-364: ELECTRON		S ASSOCIATION							
4	REQUIREMENTS									
	4.1 Design and Construe	ction								
	applicable	product drawing.	onstruction and physica							
	4.2 Materials and Finish									
	Finish: (((4.2.2 Housing: Th 4.2.3 Actuator: Th	a) Contact Area: R b) Under plate: Re c) Solder area: Re ermoplastic or The ermoplastic or The	oper alloy (Phosphor B efer to the drawing. fer to the drawing. fer to the drawing. ermoplastic High Temp ermoplastic High Temp h: Refer to the drawing	o., UL94V-0 ⊳., UL94V-0						
	4.3 Ratings									
	4.3.1 Working volt 4.3.2 Voltage: 50 4.3.3 Current: 0.5 4.3.4 Operating Te	Volts AC (per pin) Amperes (per pir)							
			Page 4	2010/10/31	TR-FM-73015L					

١SF	E DATE: 2021/01/20	REVISION: P	ECN No: EC	CN-001592	PAGE: 5 OF 10	
	erformance					
		a and Dragaduras (
. I	. Test Requirement	s and Procedures a	Summary			
	Item	Requi	rement	Stan	dard	
	Examination of Product		et requirements of ct drawing and	Visual, dimensior per applicable qu plan.		
		ELE	CTRICAL			
	ltem	Requi	rement	Stan	dard	
	Low Level Contact Resistance	100 m Ω Max. (in 40 m Ω Max. Cha		Mate connectors, measure by dry circuit, 20mV Max., 100mA Max. (EIA-364-23)		
	Insulation Resistance	500 M Ω Min.		Unmated connect 500 V DC betweet terminals. (EIA-364-21)		
	Dielectric Withstanding Voltage	No discharge, fla breakdown. Current leakage:		250 VAC Min. at minute.	acent contacts of	
	Temperature rise	30℃ Max. Chang	je allowed	Mate connector: I temperature rise until temperature ambient conditior (EIA-364-70, METHOD1,CON	at rated current stable. The $_{\rm i}$ is still air at 25 $^\circ\!{\rm C}$	

: 0.5/0.8/1.0MM PIT	CH EASY ON FPC CONN	N. SMT R/A BOTTOM CONTACT	ТҮРЕ		
DATE: 2021/01/20	REVISION: P	ECN No: ECN-001592	PAGE: 6 OF 1		
	MECH	HANICAL			
Item	Requir		dard		
Durability	20 cycles.	The sample shou the tester and full unmated the num specified at the ra 25.4 ± 3mm/min. (EIA-364-09)	Ild be mounted in ly mated and nber of cycles		
FPC Retention Force	0.03Kgf/Pin MIN	board and insert	I be soldered on a the actuator, pull beed rate of $25.4 \pm$		
Terminal /Housing Retention Force	0.10kgf MIN.	Operation Speed 25.4 ± 3 mm/min Measure the con with Tensile strer	ute. tact retention force		
Fitting Nail /Housing Retention Force	0.20kgf MIN.	Operation Speed 25.4 ± 3 mm/min	: ute. tact retention force		
Vibration	1 µs Max.	The electrical loa be 100 mA maxir contacts. Subjec harmonic motion of 0.76mm (1.52r total excursion) ir between the limit Hz. The entire fro from 10 to 55 Hz Hz, shall be trave approximately 1 r motion shall be a in each of three n perpendicular dire (EIA-364-28 Con	d condition shall num for all to a simple having amplitude mm maximum n frequency s of 10 and 55 equency range, and return to 10 ersed in minute. This pplied for 2 hours nutually ections. dition I)		
Shock (Mechanical)	1 µs Max.	50 G's (peak valu shock pulses of 1 duration. Three s direction shall be three mutually pe of the test specim The electrical loa be 100mA maxim contacts.	Subject mated connectors to 50 G's (peak value) half-sine shock pulses of 11 milliseconds duration. Three shocks in each direction shall be applied along the three mutually perpendicular axes of the test specimen (18 shocks). The electrical load condition shall be 100mA maximum for all contacts. (EIA-364-27, test condition A)		

	Aces P/N: 51503 SE							
E: 0.5/0.8/1.0MM PITCH	EASY ON FPC CONN. SMT R/A BOT	TOM CONTACT	ТҮРЕ					
SE DATE: 2021/01/20 REVISION: P ECN No: ECN-001592 PAGE: 7 OF 10								
	ENVIRONMENTA	L						
Item	Requirement	Stan	dard					
Resistance to Reflow	See Product Qualification and Test	Pre Heat : 150°C	~180 ℃,					
Soldering Heat	Sequence Group 10 (Lead Free)	60~120sec.						
		Heat : 230°C Min	., 40sec Min.					
		Peak Temp. : 260	0°CMax.					
			Dsec Max.					
		Mate module and						
		condition for 5 cy						
	See Product Qualification and Test							
Thermal Shock	Sequence Group 4	-55 +0/-3 °C, 30 minutes						
		+85 +3/-0 °C, 30 minutes						
		(EIA-364-32, test condition I)						
		Mated Connector						
	See Product Qualification and Test							
Humidity	Sequence Group 4	96 hours.						
		(EIA-364-31,Condition A, Method II)						
		Subject mated co						
		temperature life a						
Temperature life	See Product Qualification and Test	temperature life at 85℃ for 96 hours.						
	Sequence Group 5	(EIA-364-17, Test condition A)						
		Subject mated/un	mated					
		connectors to 5%						
		concentration, 35						
Salt Spray	See Product Qualification and Test							
(Only For Gold Plating)	Sequence Group 6	(II) Gold plating 1						
(Only For Gold Flating)	Sequence Group 0	(III) Gold plating 3						
		(IV) Gold plating						
		(EIA-364-26)						
<u> </u>	Tin plating:							
	Solder able area shall have	And then into solo	der hath					
	minimum of 95% solder coverage.	Temperature at 2						
Solder ability	Gold plating:	sec.						
	Solder able area shall have	(EIA-364-52)						
	minimum of 75% solder coverage	(=17-304-32)						
Hand Soldering		T : 0 T 0 T						
Temperature Resistance	Appearance: No damage	T≧350°C, 3sec a	it least.					

Note. Flowing Mixed Gas shell be conduct by customer request.



	Ac	ces P/N	1: 51	503	seric	es					
TLE: 0.5/0.8/1.0MM PITCH EASY ON F	FPC C	CONN.	SMT	R/A B	отто	M CO	NTAC	CT TY!			
EASE DATE: 2021/01/20 REVISION: P				ECN No	o: ECN-	-001592			PA	GE: 9 C	DF 10
PRODUCT QUALIFICATION A		TES	T SE			:					
					Те	st Gro	up				
Test or Examination	1	2	3	4	5	6	7	8	9	10	11
					Test	Seque	ence				
Examination of Product				1 • 7	1、6	1、4				1	1
Low Level Contact Resistance		1、5	1、4	2、10	2、9	2 \ 5				3	
Insulation Resistance				3、9	3 • 8		 				
Dielectric Withstanding Voltage				4 • 8	4 • 7						
Temperature rise	1						 				
Durability		3	<u> </u>				 				
Vibration			2				 				
Shock (Mechanical)			3								
Thermal Shock			ĺ	5							
Humidity				6							
Temperature life					5						
Salt Spray(Only For Gold Plating)						3					
Solder ability							1				
FPC Retention Force		2、4					 				
Terminal / Housing Retention Force								1			
Fitting Nail /Housing Retention Force									1		
Resistance to Soldering Heat										2	
Hand Soldering Temperature Resistance											2
Sample Size	2	4	4	4	4	4	2	4	4	4	4

Aces P/N	: 51503 series							
TITLE: 0.5/0.8/1.0MM PITCH EASY ON FPC CONN.	SMT R/A BOTTOM CONTACT	ГҮРЕ						
RELEASE DATE: 2021/01/20 REVISION: P	ECN No: ECN-001592	PAGE: 10 OF 10						
8 INSTRUCTION UPON USAGE								
Operation	Precauti	ons						
FPC/FFC Termination procedure. Connector installed on the board. 1) Lift up the actuator. Use thumb or index finger.	1) Do when yon pull out mating F Actuator opened completely. (Have adhered to the terminal FPC/FFC is mated with the co the opening of the actuator is FPC/FFC is pulled out.	Confirm whether to contact part before onnector housing when						
2) Do with the actuator opened completely, and insert it in the interior of the insertion entrance surely when you insert FPC/FFC. There are some insertion resistance because this connector has the FPC/FFC temporary retention mechanism.								
 3) Rotate down the actuator until firmly closed. It is critical that the inserted FPC/FFC is not moved and remains fully inserted. Should the FPC/FFC be moved, open the actuator and repeat the process, starting with Step 1 above. 	 2) Do not add the load mating FPC/FFC with connector housing. 							
FPC/FFC Removal 1) Lift up the actuator. 2) Carefully remove the FPC/FFC.	3) Due to the structure of the cor have string resistance to upwa support the FPC/FFC when a to it.	ard pulling; therefore,						
	•	•						